



# Product Change Notification

**Change Notification #:** 118426-00

**Change Title:** Select Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack  
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack  
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack  
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack  
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack  
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack  
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack  
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack  
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack,  
PCN 118426-00, Label,  
Label Update

**Date of Publication:** August 13, 2021

**Key Characteristics of the Change:**

Label, Label

**Forecasted Key Milestones:**

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	September 12, 2021
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## Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

- Customer label updated with UKCA logo added to the label.

Before



After



## Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

## Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU512GZX1	99A39N
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU010TZX1	99A39P
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Retail Box Single Pack	SSDPEKNU020TZX1	99A39R
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU512GZ	99A42F
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU010TZ	99A42G
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic 100 Pack	SSDPEKNU020TZ	99A42H
Intel® SSD 670p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU512GZN1	99A428
Intel® SSD 670p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU010TZN1	99A42C
Intel® SSD 670p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPEKNU020TZN1	99A42D

## PCN Revision History:

**Date of Revision:**

August 13, 2021

**Revision Number:**

00

**Reason:**

Originally Published PCN



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## 118426-00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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